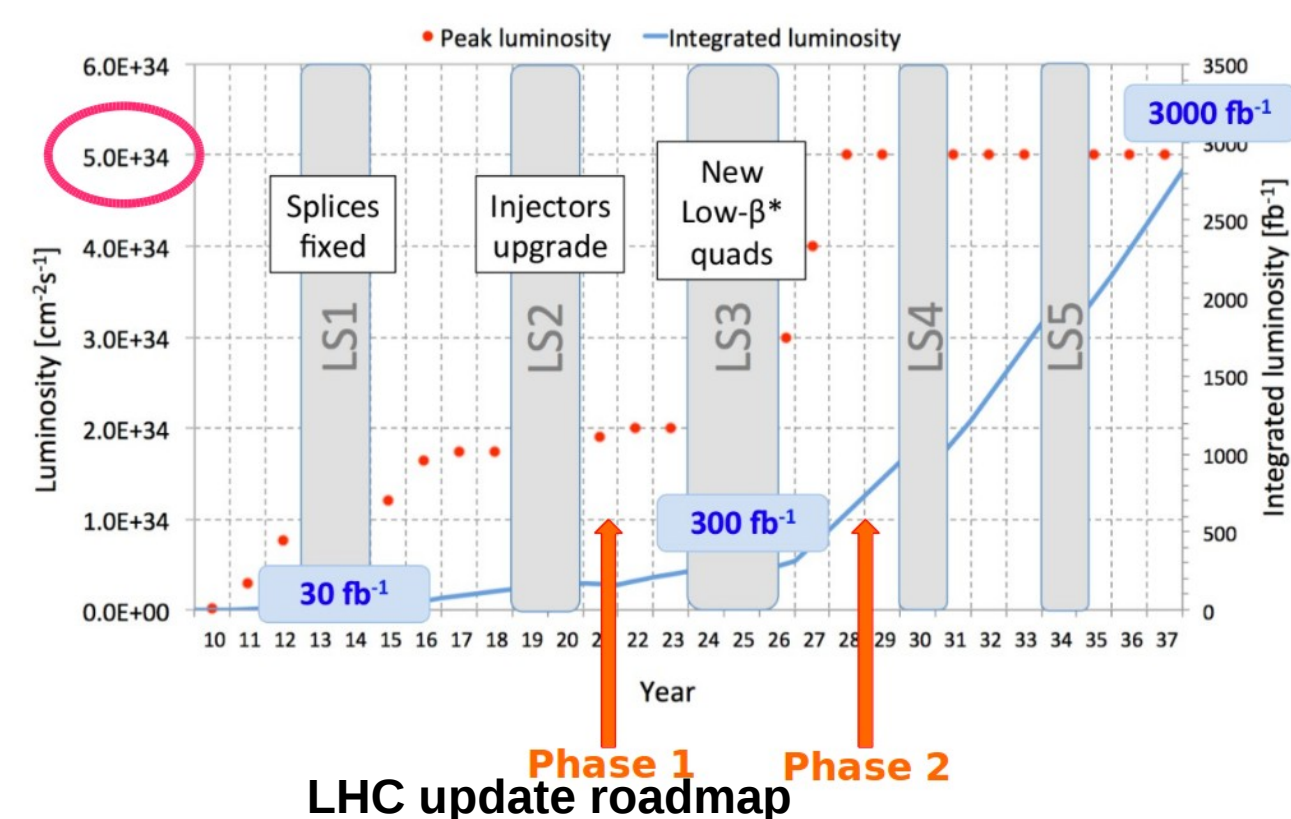
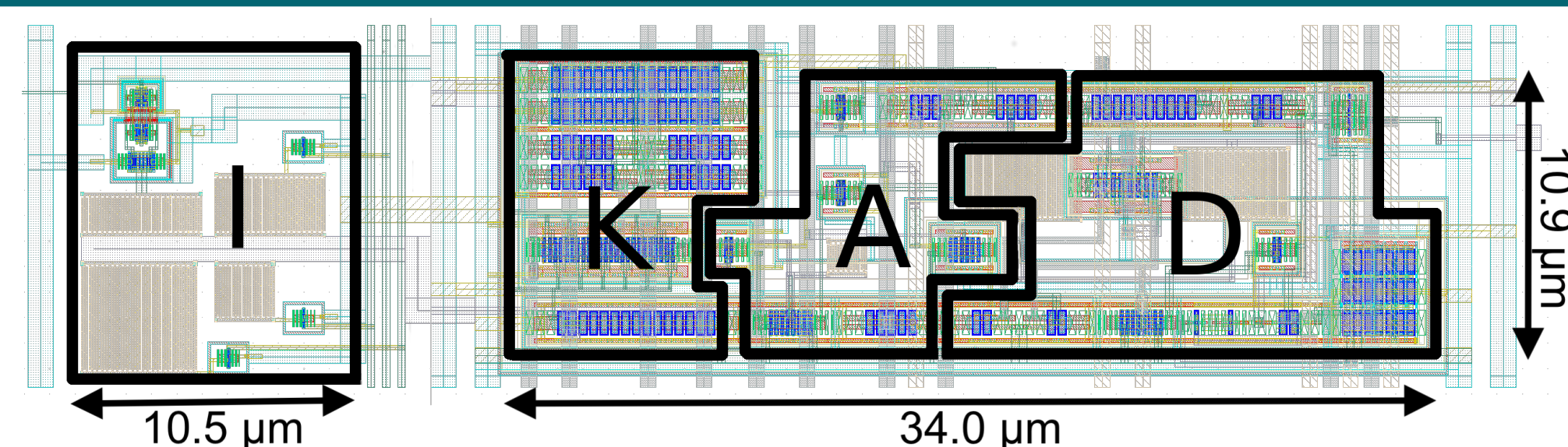


Research context and motivation

- High Energy Physics (HEP) Experiments will enter a new High Luminosity (HL) phase in order to increment statistics of rare events.
- The Large Hadron Collider (LHC) at CERN in Geneva will be upgrade to its HL-phase in 2026, reaching a peak luminosity of $5 \times 10^{34} \text{ [cm}^{-2}\text{s}^{-1}]$
- In this condition detectors electronics must be re-designed in order to cope with new requirements: radiation hardness up to $10^{17} \text{ [n cm}^{-2}]$, data rates of $3 \text{ [GHz cm}^{-2}]$ and a number of pile-up events on the order of 200.
- Standard tracking techniques will prove to be inadequate to distinguish single events on the basis of the acquired data.
- The TimeSPOT project by INFN will aim to research and develop a demonstrator of scaled down version of a tracker suitable for HL (comprising the radiation sensor, front-end (FE) electronics, read-out electronics and track-reconstruction electronics).
- In order to properly reconstruct tracks the project will adopt a 4D-Tracking techniques, which requires the particle timing information in addition to the 3D positional one.
- This work is part of the design and realization of the FE electronics for TimeSPOT.

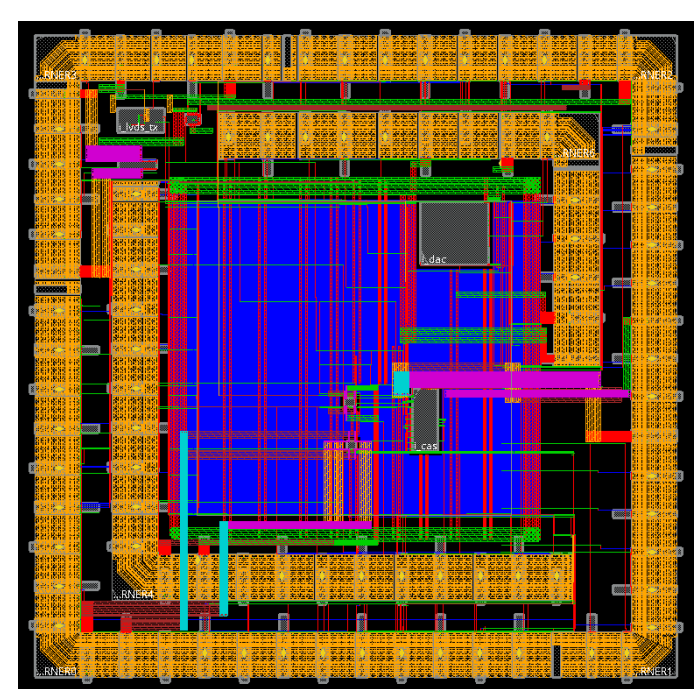


Addressed research questions/problems

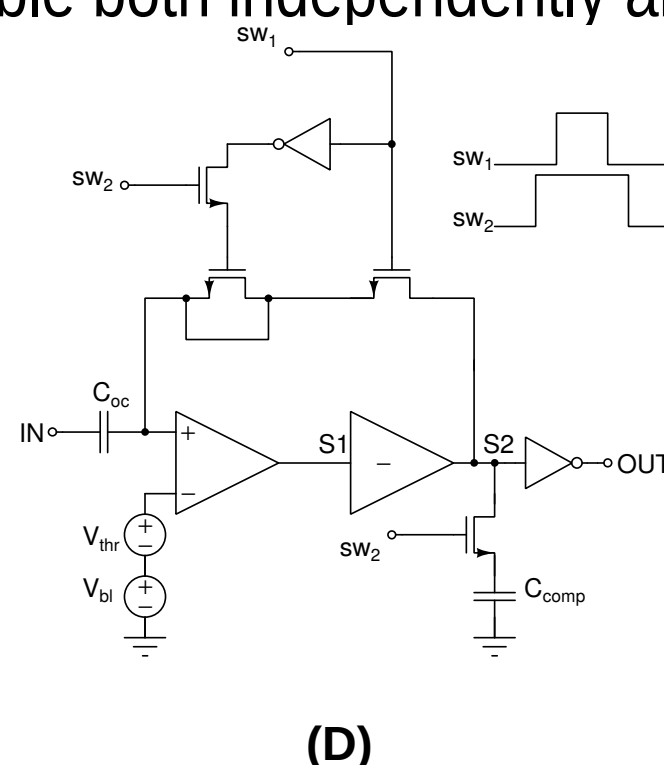


Analog FE full chain Layout

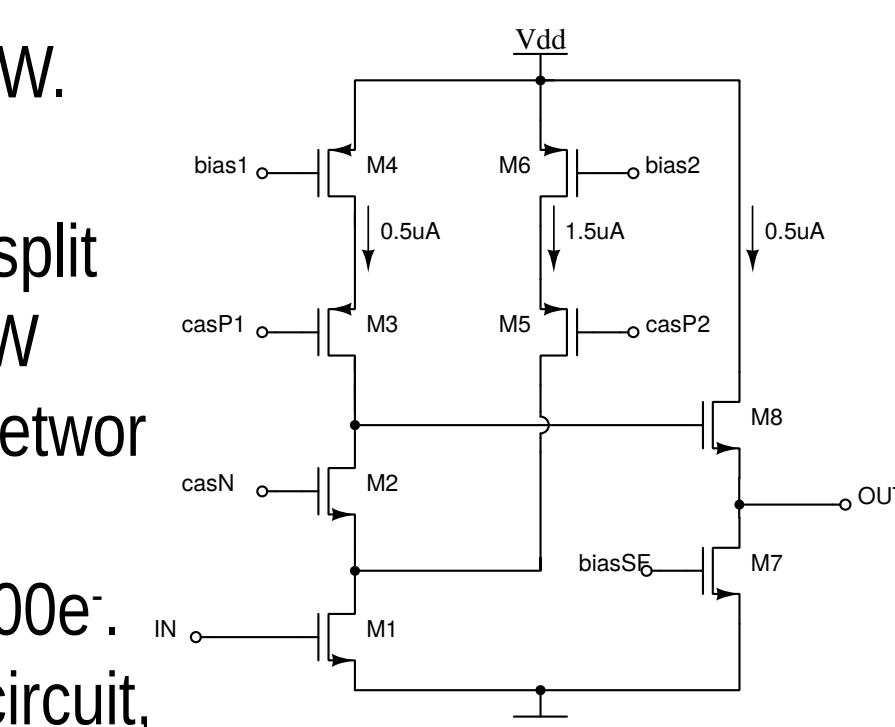
- High granularity timing pixel FE requires a low noise, small area, PVT resistant and high speed design design.
- FE architecture designed with total power budget $< 10 \text{ μW}$. Composed by:
 - Core Amplifier (A) : Telescopic Cascode Amplifier with split bias current branches, with total power consumption $< 3 \text{ μW}$
 - Charge Sensitive Amplifier CSA with active feed-back network (K) with DC leakage current compensation based on Krummenache Filter, with power $< 100 \text{ nW}$ and $\text{ENC} < 100 \text{ e}^-$.
 - Leading Edge Discriminator (D) with Offset Correction circuit, PVT aware design with power $< 3 \text{ μW}$.
 - Charge Injection Circuit (I) with variable capacitive load for sensor emulation and calibration.
- Necessity to characterize a fast and low-power system: digital IO to overcome band-width limitation: first prototype testable both independently and with the on-chip TDC.



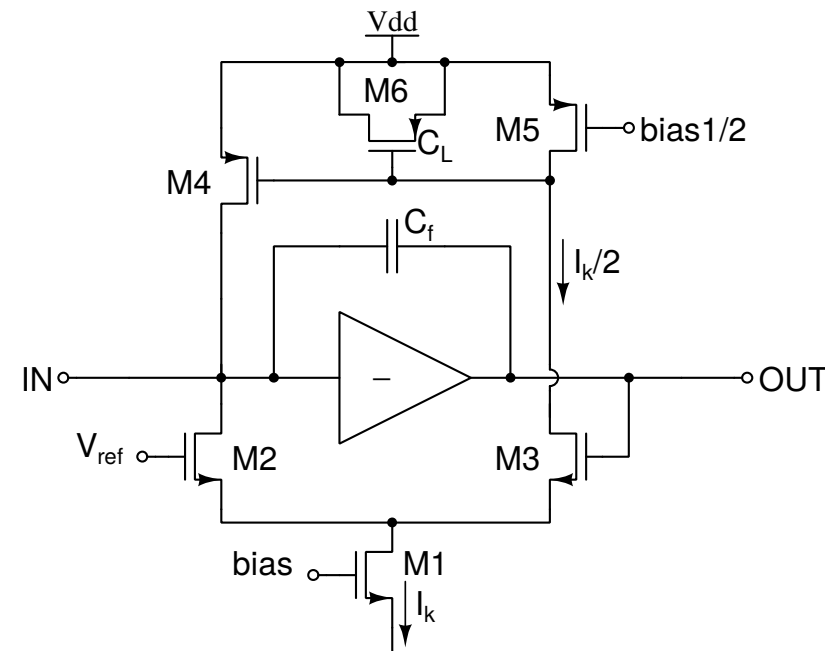
Full Chip Layout of the first prototype



(D)



(A)



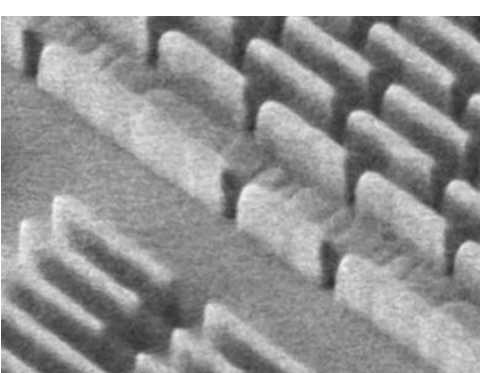
(K)

Submitted and published works

Lorenzo Piccolo, "A Timing Pixel Front-End Design for HEP Experiments in 28 nm CMOS Technology", 2019 15th Conference on Ph.D Research in Microelectronics and Electronics (PRIME)

Novel contributions

- Employment of a 28nm CMOS technology, new in the field of radiation tolerant electronics.
- Development of an architecture which aims to fulfill the requirements of pixel detectors in for HL-HEP experiments:
 - Pixel pitch of $55 \times 55 \text{ μm}^2$.
 - Timing resolution $< 100 \text{ ps}$.
 - Power consumption of $\sim 40 \text{ μW/channel}$.
 - Pixel dead time $< 1 \text{ μs}$ in order to sustain 75 KHz per-channel data-rate.
 - Integration of one TDC per channel
- Usage of a discrete-time technique to compensate per-channel variation and thus avoiding per-pixel calibration.



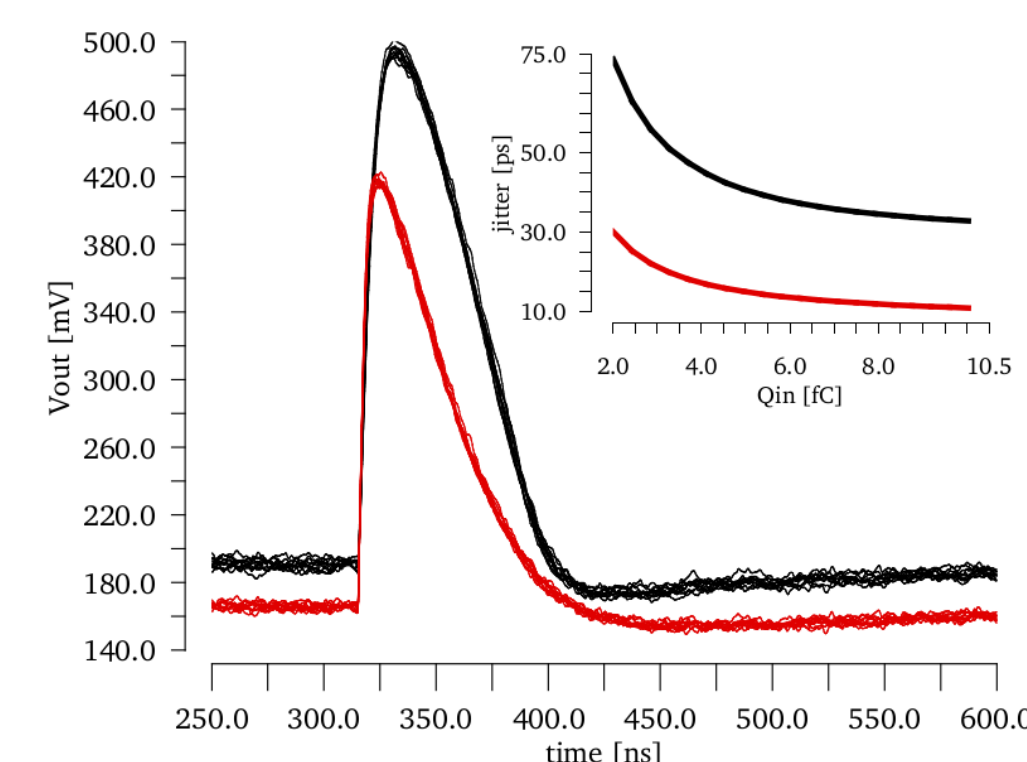
SEM photo CMOS process

Input Signal	Delta-like	Sensor
Power [μW]	4.1	7.2
G [mV fC ⁻¹]	190	168
σ _n [mV]	2.8	2.0
ENC [e]	94	77
t _{pk} [ns]	16.4	7.7
t _A [ns]	2.1	2.1
TOT [ns]	100	98
SR [mV ns ⁻¹]	53	98
σ _j [ps]	54	21
σ _p [ps]	66	65
σ _{mm} [ps]	33	26

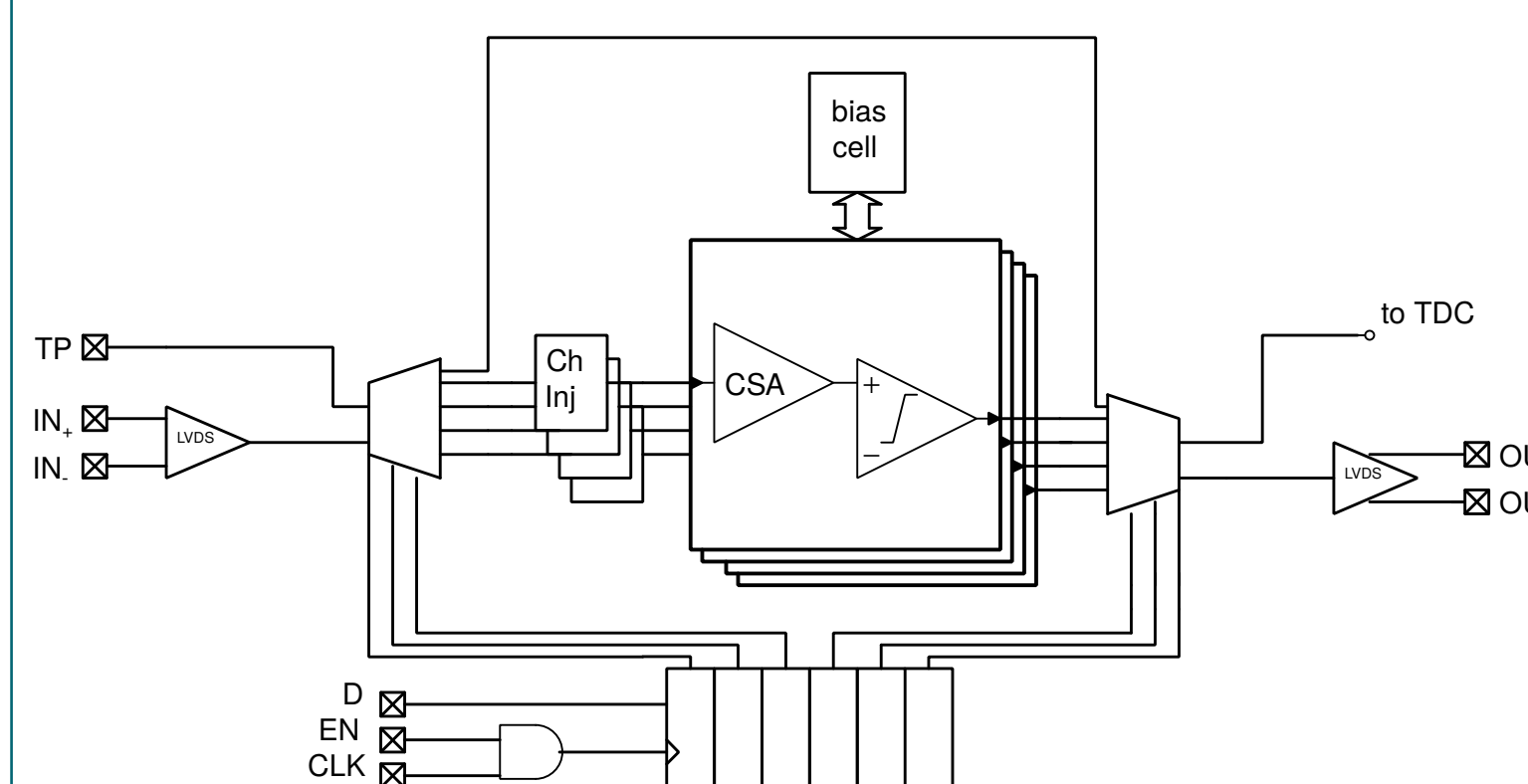
Simulated expected FE performances

Adopted methodologies

- Circuit design and simulation carried out using industry standard EDA tools and CAD.
- Conjoint development and optimization of FE electronics and silicon sensor (impedance matching and signal characteristics).
- Montecarlo simulations for per chip-and per pixel variation due to process and mismatch variations.
- FPGA-based experimental setup for precise and fast control of compensation phase, system pulsing and analog reference setup.



Simulated CSA signal



Schematic of implement test structure with core blocks (repeated in 8 parallel channels)

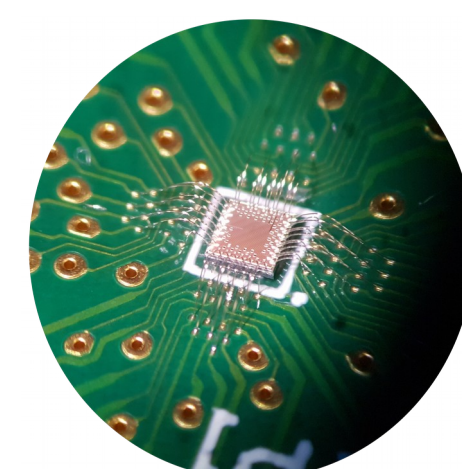
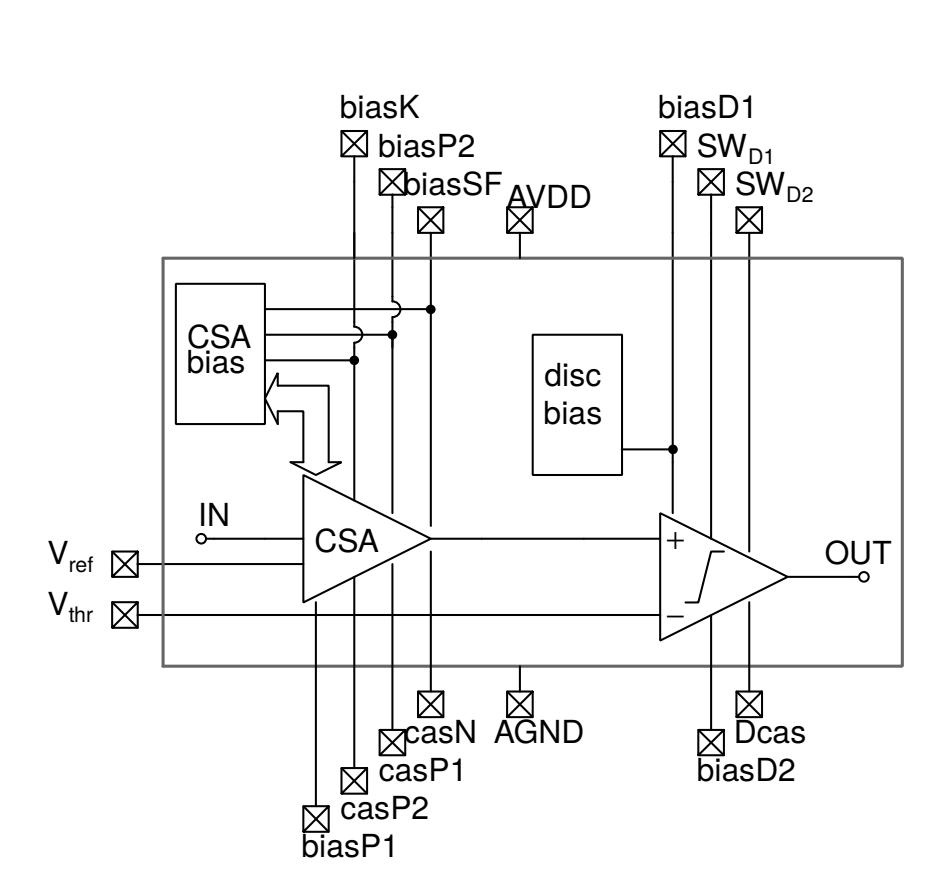


Photo of the first test chip wire bonded to its test board. Now under test



Detailed schematic of the system with essential external references

Future work

- Ongoing tests on first prototype, which aims to obtain a complete operation and performance characterization.
- Radiation damage tests on first prototype.
- Design of an integrated-on pixel time-walk correction based on Constant Fraction Discriminator (CFD) of Time over Threshold (ToT) measurement.
- Realization of a second prototype chip with the full FE pixel chain organized in a pixel matrix with service blocks and digital I/O. This chip will be coupled via bump-bonding with now-under-test sensor. The second design will be submitted on 4/2020.

List of attended classes

- 01CLPRV – Experimental modeling (10/2018, 6)
- 01RONKG – Python in the Lab (2/2019, 4)
- 03QRHRV – Microelectronics for radiation detection II (6/2019, 4)
- 02LWHRV – Communication (8/2019, 1)
- 01SHMRV – Entrepreneurial Finance (8/2019, 1)
- VIII International Course "Detectors and Electronics for High Energy Physics Astrophysics, Space and Medical Applications" (2/2019, external activity ,30h)